



Design of High Dynamic Range DAC

Outline

- Choice of the DAC architecture.
- Design and test results of a 12 bit DAC. (MEMS)
- Design and test results of a 14 bit DAC. (ILC Si-W Ecal)
- Summary of the DACs main features.





DAC architecture

Switched Capacitors Array & Dynamic Element Matching

- Power consumption constraint => **switched capacitors** architecture.
- The linearity will be limited by the **matching errors** of the capacitors.
- => Linearization methods have to be used.
- The **Dynamic Element Matching** (DEM) is commonly used in **high** resolution multi bit Sigma-Delta converters.
- The DEM turns harmonic distortion into noise, this noise is then reduced by the converter's low pass filter.





DAC architecture

Dynamic Element Matching : block diagram

The DEM algorithm has to be coupled to a **Thermometer DAC**.

Such n bit DAC uses 2ⁿ equally weighted converters.



Without DEM : Input code = 3 => Vout = DAC1 + DAC2 + DAC3

With DEM: the selected 3 DACs are different for each conversion (scrambling)

The effects of the matching errors are spread over the whole dynamic range.



Segmented array of switched capacitors



The DEM efficiency has to be evaluated for such a network

=> high level simulation : fast and exhaustive evaluation.





Simulation software

- Labview was used for the simulation and for the test bench control.
- Simulated and measured data are processed in the same way by the block labelled *Data Analysis*. This block computes the INL, DNL,THD, SNR, ... It also extracts the capacitors matching errors.





I N 2 P 3

Design of a 12 bit, 5 Msps Digital to Analog Converter

Simulation software : spectral analysis

Configuration Analyse spectrale			
SINUS	DAC	Analyse	
Sinus Mag 2048 Pattern size 4095 Nb de cycles en RAM 14 Fs DAC / Fs ADC 1 Fs DAC / Fs ADC 5.0000000M 5.0000000M Substantiation Absolution Nb sp / T pour DAC NB sp / T pour ADC 292.571 292.571 Frequence sinus 17089.84375	MSB array LSB array Ideal Ideal DEM MSB DEM LSB Sans DEM Image: Constraint of the second se	Quantification sortie DAC Quantification 16 bits window Rectangle Fréquence basse pour IBSNR 100 Fréquence haute pour IBSNR 2000 Nb samples à rejeter 100 Nb samples pour analyse 131072 Créer Fichier	











Differential implementation

- Inherits the OTA designed at LPSC for a pipeline ADC (Dzahini, Rarbi).
- Low sensitivity to parasitic capacitors (substrate coupling):
 - Sum_LSB : very low sensitivity on LSB side.
 - Sum_MSB : OTA 90dB open loop gain => $\Delta V=0$.
 - Parasitic capacitors in parallel with each $C_i =>$ matching errors : processed by the DEM algorithm.
- Sensitive component : Cseg, must match the MSB array mean value.





N 2 P 3

Power consumption - Layout

Vdd	= 3.3 V			
DEM	=> 0.3 mW @ 5MHz			
OTA	=> 2.2 mW			
BIAS	=> 2.5 mW			
DAC12	=> 5 mW			
Idle mode : < 1 µW				
1300x1200 µm² = 1.6 mm²				







Test results – Matching errors in a 63 capacitor array

- 15 chips tested
- Systematic matching error : from 0.8% up to 1.8%
- Gradient not constant over the array => effect not cancelled by a Common Centroid layout.







High level simulation versus test results - INL and RMS noise

The DEM improves the INL by a factor of 8 => 3 bits







Conclusion for the 12 bit DAC

- The DAC satisfies the constraints of the MEMS sensor project. (Power consumption, Sampling rate, INL, THD, IBSNR).
- The capacitors matching errors are larger than expected in a CMOS 0.35µ process.
- The DEM improves the INL by a factor of 8 (3 bits) and induces a 1 LSB RMS noise. (without external filter)
- Our high level simulation is a fast and reliable tool.





Block diagram

- Number of capacitors reduced compared to the 12 bit DAC (144/191).
- Very low sensitivity to parasitic capacitors (substrate coupling).
- Cf₁, Cs₂, MSB array mean value : matching has to be better than 0.3%.
- Cf₁ : trimming capability for this first 14 bit prototype (0.1C step).







Power consumption - Layout

- Vdd = 3.3 V
- DEM => 0.2 mW @ 5MHz
- OTA => 2 x 2.2 mW
- BIAS => 2.5 mW
- DAC14 => 7.1 mW
- Idle mode : $< 1\mu W$

 $1300 \times 1100 \ \mu m^2 = 1.4 \ mm^2$







Test results – Matching errors in a 31 capacitor array

- 9 chips successfully tested.
- Systematic matching error : from 0.25% to 0.4%
- Mismatch due to interconnections : < 0.1% (AV_extracted







Test results – INL and RMS noise

The DEM improves the INL by a factor of 2

Without DEM

With **DEM**







Process reliability

Spread of oxyde thickness for 8 runs in 2008 & 2009







Main features of the 2 DACs

Static and dynamic parameters (without external filter)

	12 bit DAC		14 bit DAC	
	DEM on	DEM off	DEM on	DEM off
Area (mm ²)	1.6		1.4	
Power (mW)	5		7	
Frequency (MHz)	5		5	
INL (LSB / µV)	0.3 / <mark>150</mark>	2.5 / 1200	0.5 / <mark>60</mark>	1.2 / <mark>150</mark>
RMS noise (LSB / µV)	1 / 500 **	0.15 / <mark>70</mark>	0.6 / <mark>70</mark> *	0.5 / <mark>60</mark> *
THD (dB)	-87	-67	-96	-89
SNR (dB)	66 **	77	81 *	82 *
SFDR (dB)	86	68	96	92
ENOB	10.7 **	10.8	13.2 *	13.2 *

** limited by the DEM noise

* limited by the testing board noise





Conclusion : Process reliability – Trimming issue

- The matching errors are much smaller in the 14 bit DAC compared to the 12 bit DAC, whereas the capacitor arrays are similar (larger dummies in the 14 bit DAC).
- The **spread of the oxide thickness** for the **12 bit DAC** run is **twice the spread** for the **14 bit DAC** run (it was the worst among the chips submitted by LPSC in 2008/2009).
- The optimal trimming value is the same for the 9 tested DAC. The same value is also found with high level simulation.
- For this run, the DAC satisfies the constraints of a 14 bit design without trimming. (since the optimal value can be predicted).
- A self trimmed 14 (or 15 ?) bit DAC will be submitted in 2010.